Surface Mount Schottky Power Rectifier

SMA Power Surface Mount Package

MBRA210L, NRVBA210L, NRVBA210LN

This device employs the Schottky Barrier principle in a metal−to−silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes. Typical applications are AC−DC and DC−DC converters, reverse battery protection, and "Oring" of multiple supply voltages and any other application where performance and size are critical.

Features

- Ultra Low V_F
- 1st in the Market Place with a 10 V_R Schottky Rectifier
- Compact Package with J−Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guardring for Over−Voltage Protection
- Optimized for Low Forward Voltage
- NRVBA Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable*
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL 94 V−0 @ 0.125 in
- Weight: 70 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead
- ESD Ratings:
  - Machine Model = C
  - Human Body Model = 3A

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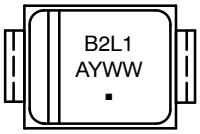
SCHOTTKY BARRIER RECTIFIER 2 AMPERES 10 VOLTS

SMA
CASE 403D

MARKING DIAGRAM



B2L1 = Specific Device Code
A = Assembly Location**
Y = Year
WW = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

**The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

ORDERING INFORMATION

Device	Package	Shipping†
MBRA210LT3G	SMA (Pb−Free)	5,000 / Tape & Reel
NRVBA210LT3G*	SMA (Pb−Free)	5,000 / Tape & Reel
NRVBA210LNT3G*	SMA (Pb−Free)	5,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	10	V
Average Rectified Forward Current (At Rated V_R, T_L = 110°C)	I_O	2.0	A
Non−Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	160	A
Storage/Operating Case Temperature Operating Junction Temperature	T_{stg}, T_C T_J	−55 to +125	°C
Voltage Rate of Change (Rated V_R, T_J = 25°C)	dv/dt	10,000	V/μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Min Pad	1 Inch Pad	Unit
Thermal Resistance, Junction−to−Lead Thermal Resistance, Junction−to−Ambient	$R_{\theta JL}$ $R_{\theta JA}$	22 150	15 81	°C/W

ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 1)	V_F	**T_J = 25°C**	**T_J = 100°C**	V
(I_F = 0.1 A) (I_F = 1.0 A) (I_F = 2.0 A)		0.260 0.325 0.350	0.15 0.23 0.26	
Maximum Instantaneous Reverse Current	I_R	**T_J = 25°C**	**T_J = 100°C**	mA
(V_R = 5.0 V) (V_R = 10 V)		0.25 0.70	40 60	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width ≤ 250 μs, Duty Cycle ≤ 2%.

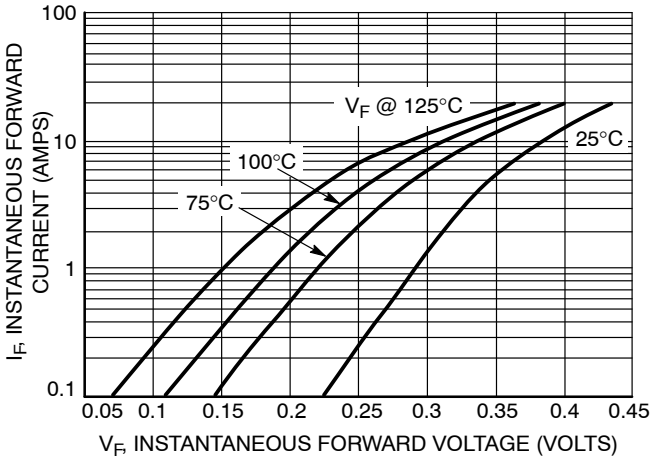


Figure 1. Typical Forward Voltage

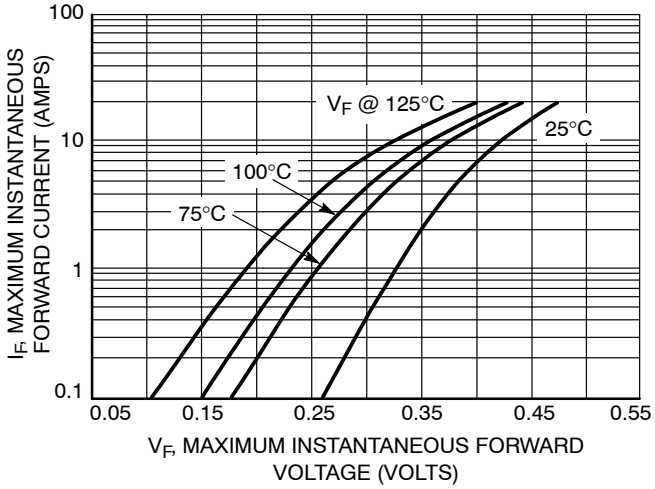


Figure 2. Maximum Forward Voltage

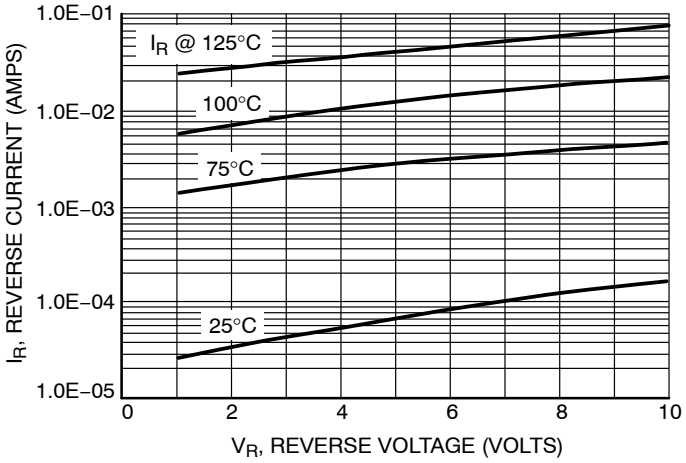


Figure 3. Typical Reverse Current

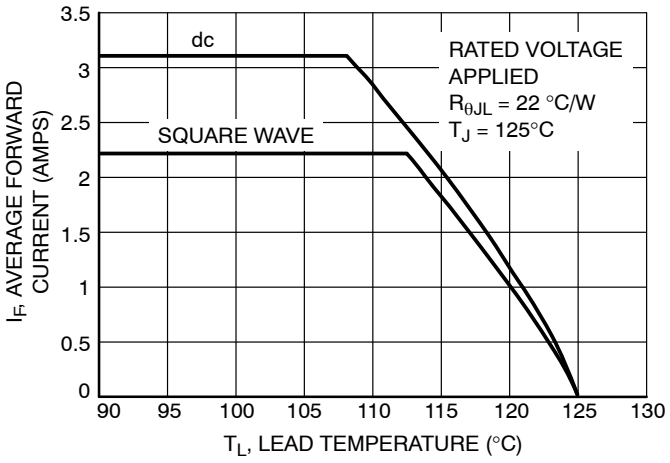


Figure 4. Current Derating – Junction to Lead

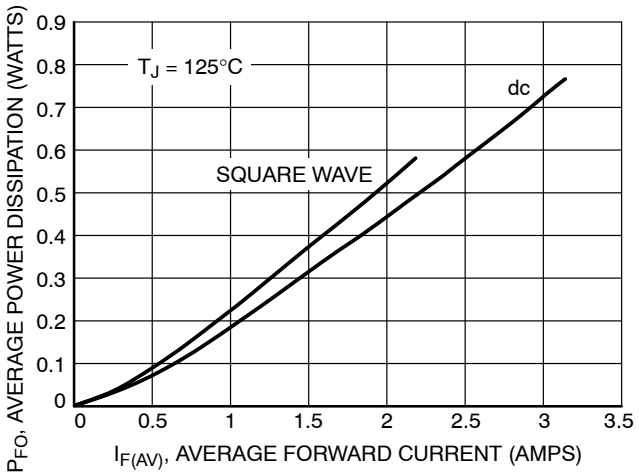


Figure 5. Forward Power Dissipation

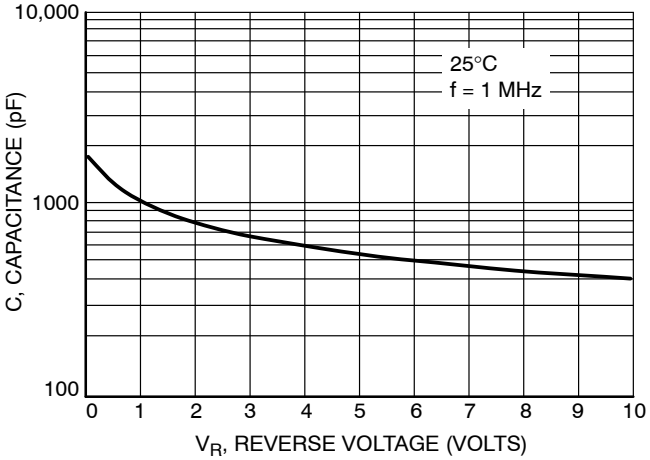


Figure 6. Typical Capacitance

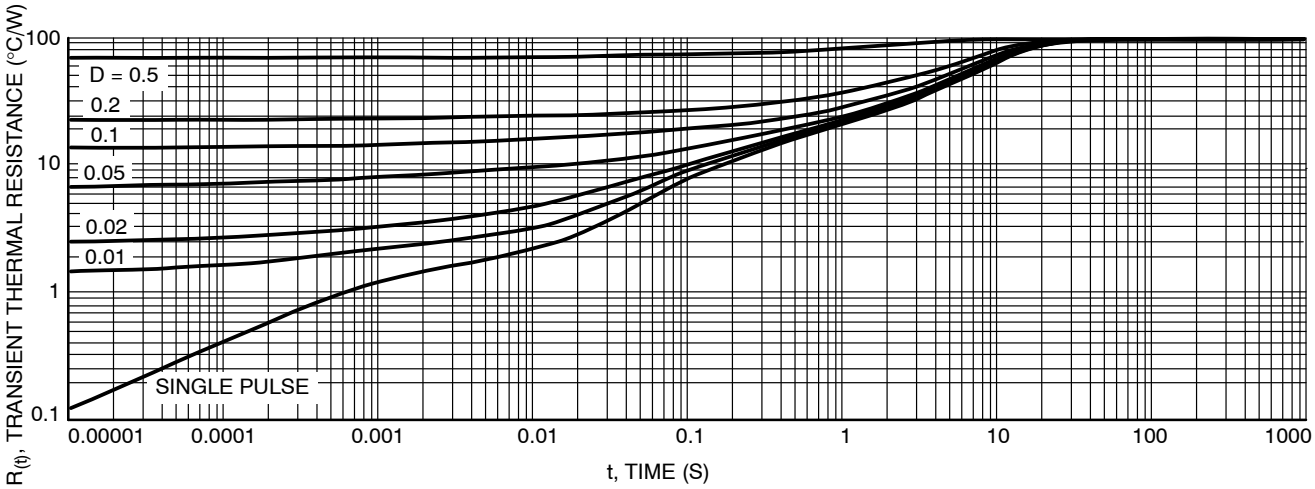


Figure 7. Thermal Response, Junction to Ambient (min pad)

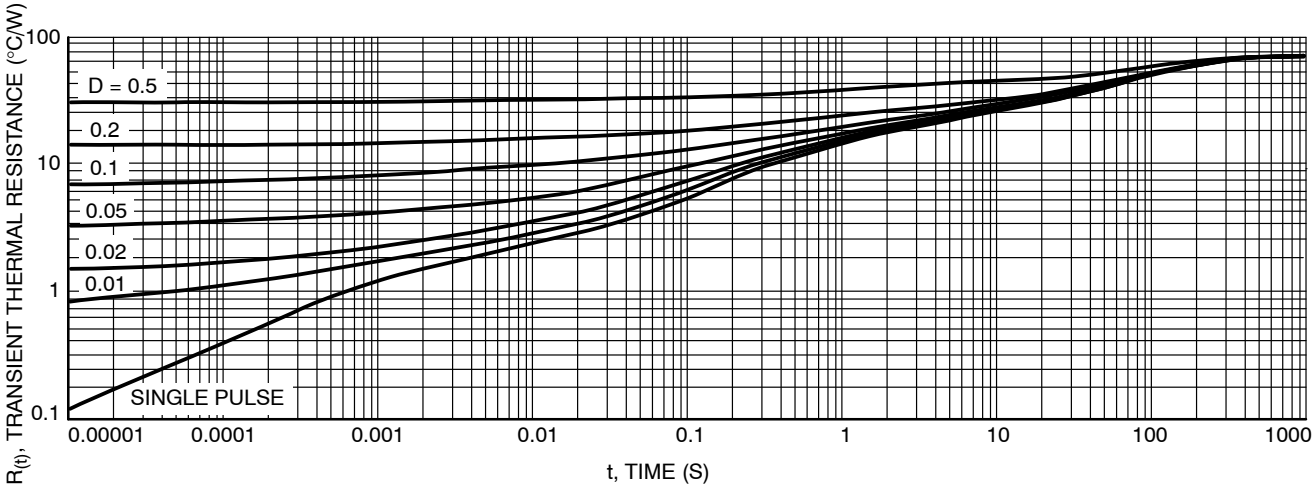


Figure 8. Thermal Response, Junction to Ambient (1 inch pad)

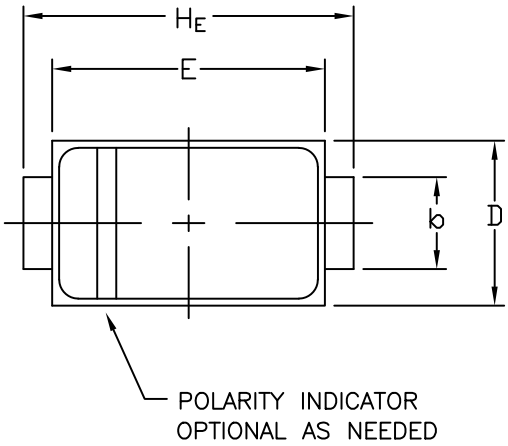
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

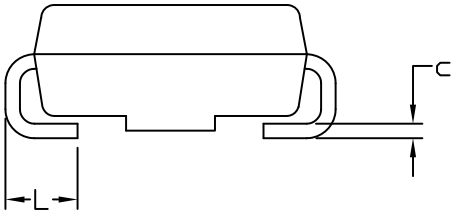
SMA
CASE 403D
ISSUE J

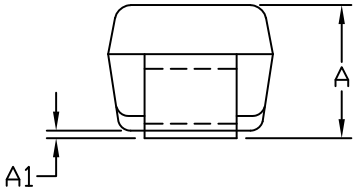
DATE 22 OCT 2021

STYLE 1 STYLE 2

SCALE 1:1







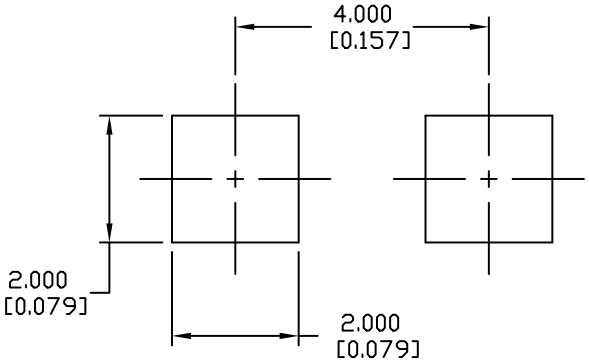
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCHES
3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L.

	MILLIMETERS			INCHES		
DIM	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	1.97	2.10	2.20	0.078	0.083	0.087
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.27	1.45	1.63	0.050	0.057	0.064
c	0.15	0.28	0.41	0.006	0.011	0.016
D	2.29	2.60	2.92	0.090	0.103	0.115
E	4.06	4.32	4.57	0.160	0.170	0.180
H_E	4.83	5.21	5.59	0.190	0.205	0.220
L	0.76	1.14	1.52	0.030	0.045	0.060

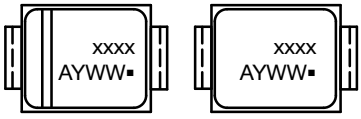
STYLE 1:
PIN 1. CATHODE (POLARITY BAND)
2. ANODE

STYLE 2:
NO POLARITY



RECOMMENDED
MOUNTING FOOTPRINT

GENERIC
MARKING DIAGRAM*



STYLE 1 STYLE 2

xxxx = Specific Device Code
A = Assembly Location
Y = Year
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▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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